nextron®

NEXTRONICS ENGINEERING CORP.

Taipei, Taiwan, Headquarters

2F, No. 31, Lane 169, Kang Ning Street,
Hsi Chih District, New Taipei City, Taiwan, R.O.C.
TEL: +886-2-6616-2000
FAX: +886-2-8695-1177
E-mail: sales@nextron.com.tw
www.nextron.com.cn
www.leanpac.com

Guangzhou, China, Factory

No. 24, Guanyong Village, Shilian Highway, Shiji Town, Panyu District, Guangzhou City, Guangdong Province, China
Zip Code：511450
TEL: +86-20-8455-1166
FAX: +86-20-8455-1168
E-mail: sales@nextronnpt.com

Kunshan, China, Office

Room 216, Ri Yue Xing International Business Centre, No. 1126, Chang Jiang South Road, Development District, Kun Shan City, Jiang Su Province, China
TEL: +86-512-5791-1858
FAX: +86-512-5791-1880
E-mail: james@interconn.com.cn

Shenzhen, China, Office

TEL: +86-20-8455-1166, EXT: 504
FAX: +86-20-8455-9707
E-mail: allon@interconn.com.cn
linda@interconn.com.cn

Yokohama, Japan, Office

589-13, Hirado-cho, Totsuka-ku, Yokohama City, Kanagawa-ken 244-0803, Japan
Tel: +81-90-2623-4617
Fax: +81-45-392-8803
Email: jiwata@ccai.jp

PalPilot Nextron USA, Santa Clara Office

3000 Kenneth St. Santa Clara CA 95054,USA
TEL: +1 408 855 8866
FAX: +1 408 855 8868
Email: jimmyy@palpilot.com

PalPilot Nextron USA, Tustin Office

15991 Red Hill Ave Suite 102 Tustin CA 92780
TEL: +1 714 460 0718
FAX: +1 714 460 0728
Email: jimmyy@palpilot.com

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nextron®

CONNECTING THE NEXT ELECTRONICS

High Speed I/O Connector

- SFP/SFP+ Series
- XFP Series
- QSFP Series
- MiniSAS HD Series



TL 9000
ISO14001
OHSAS18001
ISO13485

nextron®
NEXTRONICS ENGINEERING CORP.

High Speed I/O Connector Roadmap

One of the best in Asia:

- ***High speed, industrial & medical connector manufacturer***
- ***High speed backplane, accessories and subsystem maker***

1987 Nextronics Engineering Corp. was established in Taiwan
1997 Start producing medical connector
1997 Established the production base in Panyu, Guangdong, China
1997 Established Nextronics Engneering(H.K.) Limited
1998 Won the Taiwan Seventh Small & Medium Enterprise Award
1998 Nextronics first pressfit backplane assembly
1998 Complete vertical integration of the pressfit-type connectors
2000 Complete backplane pressfit vertical integration;
2004 Vertically integrated industrial chassis assembly and testing
2010 Nextronics Guangdong Factory completed the renovation
2010 Established Kunshan Nextronics Engineering Corp.
2010 Obtained TS16949, ISO14001, OHSAS18001, ISO13485 certification
2011 Obtained TL9000 certification
2012 Nextronics enters the emerging stock market in Taiwan
2013 Nextronics goes public in Taiwan. OTC Stock No. 8147



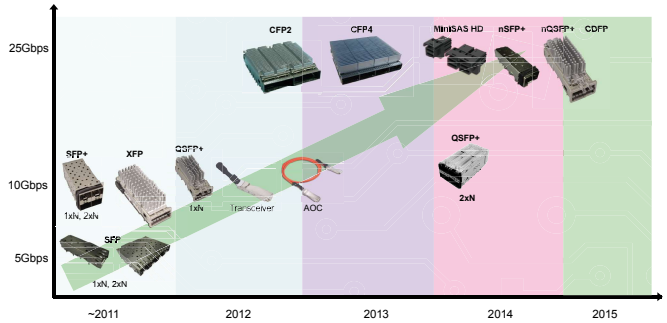
QUENSH Structure & Milestone



2009 ISO9001
2010 TL9000 ISO14001 OHSAS18001
2011 ISO13485



TL9000 ISO14001 OHSAS18001

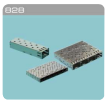



827
SFP
Connector, SMT 20pos.

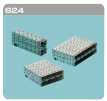

832
SFP+
Connector, SMT 20pos.

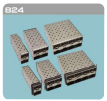

831
XFP
Connector, SMT, 30pos.


835
QSFP
Connector, SMT, 38pos.


828
SFP
Cage 1x1/1x2/1x4/1x6 solder/ pressfit tail, normal/PCIe type


828
SFP +
Cage 1x1/1x2/1x4/1x6 solder/ pressfit tail, normal/PCIe type EMI gasket/spring


824
SFP
2x1/2x2/2x3/2x4/2x6/2x8 pressfit tail,
lightpipe options


824
SFP+
2x1/2x2/2x3/2x4/2x6/2x8 pressfit tail,
lightpipe options
EMI gasket/spring


834
QSFP
Solder/pressfit tail
Behind bezel/Thrubezel/EMI gasket
Cage 1x1/1x3/1x6
Heatsink for PCI/SAN/Networking


838
XFP
Cage 1x1
Heatsink for PCI/SAN/ Networking


HO2
MiniSAS HD
Internal Connector
1x1/1x2/1x4
Right Angle Receptacle
Vertical
Pressfit tail


HO2
MiniSAS HD
External Connector
1x1/1x2/1x4
Right Angle Receptacle
Pressfit tail

High Speed I/O Connector Table

Port Type	SFP	SFP+	SFP+	nSFP+	XFP	QSFP	QSFP+10
Datarate	4G	10G	16G	25G/28G	10G	4G	10G
Specification	INF-8074i	SFF-8431 SFF-8432 SFF-8083 SFF-8084 SFF-8433	SFF-8081 SFF-8431 SFF-8432 SFF-8084 SFF-8433	SFF-8402 SFF-8431 SFF-8432 SFF-8084 SFF-8433	MSA INF-8077i	INF-8438i	SFF-8436E SFF-8635
Datarate per Lane	4G	10G	16G	25G/28G	10G	4G	10G
No. of Lanes	1	1	1	1	1	4	4
Datarate per Port	4G	10G	16G	25G+	10G	16G	40G
Panel Cutout Size for single port	W: 15.25mm H: 10.40mm	W: 15.45mm H: 10.40mm	W: 15.45mm H: 10.40mm	W: 15.45mm H:10.40mm	W: 19.5mm H: 9.7mm	Behind bezel W: 19.5mm H: 9.7mm Thru bezel Elastomer Gasket W: 20.0mm H: 10.15mm	Behind bezel W: 19.5mm H: 9.7mm Thru bezel Elastomer Gasket W: 20.0mm H: 10.15mm
No. of ports in 365mm	24	24	24	24	18	18	18
Types of Assembly	Solder Pressfit	Solder Pressfit	Solder Pressfit	Solder Pressfit	Pressfit	Pressfit	Pressfit
Single – Nextron Types of Ports	1x1, 1x2, 1x4, 1x6	1x1, 1x2, 1x4, 1x6	1x1, 1x2, 1x4, 1x6	-	1x1	1x1,1x2, 1x3,1x4, 1x6	1x1,1x2, 1x3,1x4, 1x6
Single – Availability	Yes	Yes	Yes	Under Development	Yes	1x1:Yes 1x6 Behind bezel:Yes Other: Under Development	1x1:Yes 1x6 Behind bezel:Yes Other: Under Development
Stackable – Nextron Types of Ports	2x1, 2x2, 2x3, 2x4, 2x5,2x6, 2x8	2x1, 2x2, 2x3, 2x4, 2x5,2x6, 2x8	2x1, 2x2, 2x3, 2x4, 2x5,2x6, 2x8	-	-	2x1,2x2,2x3	2x1,2x2,2x3
Stackable – Availability	Yes	Yes	Yes	-	-	Under Development	Under Development
Belly to Belly Min. PCB thickness(mm)	SFP/SFP+ 1x1: 4.5mm SFP/SFP+ 1x2,1x4,1x6: 3.05mm	SFP/SFP+ 1x1: 4.5mm SFP/SFP+ 1x2,1x4,1x6: 3.05mm	SFP/SFP+ 1x1: 4.5mm SFP/SFP+ 1x2,1x4,1x6: 3.05mm	-	2.7	Thru bezel: 2.2mm Behind bezel: 2.7mm Elastomer Gasket: 3.0mm	Thru bezel: 2.2mm Behind bezel: 2.7mm Elastomer Gasket: 3.0mm

Port Type	QSFP+14G	QSFP+28	MiniSAS HD	MiniSAS HD	CFP	CFP2	CFP4	CXP	CXP	CXP	CDFP
Datarate	14G	25G/28G	12G	24G	10G	25G/28G	25G/28G	10G	14G	28G	25G/28G
Specification	SFF-8682 SFF-8683 SFF-8685	SFF-8661 SFF-8662 SFF-8663 SFF-8665 SFF-8672	SAS-3 SFF-8644 SFF-8636 SFF-8449 SFF-8643	TBD SFF-8636 SFF-8449 SFF-8645	MSA	CFP MSA	CFP MSA	EIA-985/ SFF-8642 IBTA QDR	SFF8647 IBTA FDR 802.3ba	SFF8648 SFF8647 IBTA EDR 802.3bj	TBD
Datarate per Lane	14G	25G/28G	12G	24G	10G	25G/28G	25G/28G	10G	14G	28G	25G/28G
No. of Lanes	4	4	4	4	10	4	4	12	12	12	16
Datarate per Port	56G	100G+	48G	96G	100G	100G+	100G+	120G	168G	336G	400G+
Panel Cutout Size for single port	Behind bezel W: 19.5mm H: 9.7mm Thru bezel Elastomer Gasket W: 20.0mm H: 10.15mm	Behind bezel W: 19.5mm H: 9.7mm Thru bezel Elastomer Gasket W: 20.0mm H: 10.15mm	W: 11.90mm H: 12.07mm *External type	W: 11.90mm H: 12.07mm *External type	W85.6mm H:17.6mm	W:86.35mm H:14.3mm	W:90.1mm H:11.15mm	W23.5mm H12.1mm	W23.5mm H12.1mm	W23.5mm H12.1mm	TBD
No. of ports in 365mm	18	18	-	-	4	8	16	7	7	7	11
Types of Assembly	Pressfit	Pressfit	Pressfit	Pressfit	Screw	Pressfit	Pressfit	Pressfit	Pressfit	Pressfit	TBD
Single – Nextron Types of Ports	1x1,1x2, 1x3,1x4, 1x6	1x1,1x2, 1x3,1x4, 1x6	1x1, 1x2, 1x4	1x1, 1x2, 1x4	Single cage	Single Cage Dual Cage	Single Cage Quad Cage	Single cage	Single cage	Single cage	TBD
Single – Availability	1x1:Yes 1x6 Behind bezel:Yes Other: Under Development	1x1:Yes 1x6 Behind bezel:Yes Other: Under Development	Yes	Under Development	No	Co-develop with Yamaichi	Co-develop with Yamaichi	No	No	No	Under Developmebt
Stackable – Nextron Types of Ports	2x1,2x2,2x3	2x1,2x2,2x3	-	-	-	-	-	-	-	-	-
Stackable – Availability	Under Development	Under Development	-	-	-	-	-	-	-	-	-
Belly to Belly Min. PCB thickness(mm)	Thru bezel: 2.2mm Behind bezel: 2.7mm Elastomer Gasket: 3.0mm	Thru bezel: 2.2mm Behind bezel: 2.7mm Elastomer Gasket: 3.0mm	-	-	-	3.0mm	3.0mm	-	-	-	-

High Speed I/O Connector

SFP 4Gbps Connector

827 Series

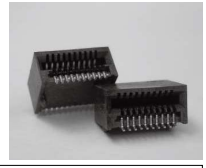
Technical Data

Material

- Insulator: Thermoplastic, UL 94V-0, black
- Contact: Copper alloy with Au plated

Applications and Features

- Designs are based on the industry standard SFP Multi-Source Agreement (MSA).
- The SFP board mount connector is 20 position and 0.8mm pitch.
- High Speed Contact Design.
- High temp and IR reflow compatible versions are available.

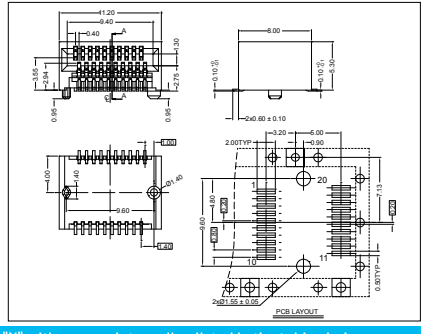


Electrical

- Current Rating: 0.5 Amps Max
- Contact Resistance: 20 mΩ Max
- Voltage Rating: 30V AC / Contact Max.
- Insulator Resistance: 1000 MΩ Min.

Mechanical

- Insertion Force: 40N Max
- Extraction Force: 11.5N Max
- Mechanical Operations: 100 cycles
- Working Temperature: -55˚C To +85˚C



Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8270000X0X000

Plating Type

Definition	Code
Au 15u"	0
Au 30u"	1

Packag Type

Definition	Code
Tape&Reel	0
Tray	1

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

SFP+ 10Gbps Connector

832 Series

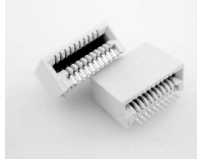
Technical Data

Material

- Insulators: Thermoplastic, UL 94V-0,Natural
- Contact: Copper Alloy With Au plated

Applications and Features

- Designs are based on the industry standard SFP Multi-Source Agreement (MSA).
- The SFP+ board mount connector is 20 position and 0.8mm pitch.
- High speed contact design.
- High temp and IR reflow compatible versions are available.

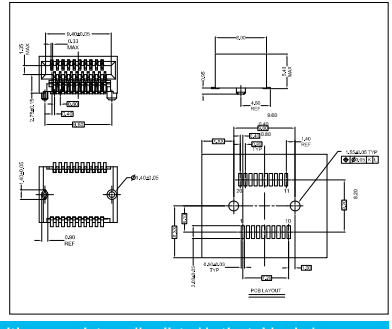


Electrical

- Current Rating: 0.5 Amps Max
- Contact Resistance: 30mΩ Max
- Voltage Rating: 30V AC/Contact
- Insulator Resistance: 1000 mΩ Min

Mechanical

- Transceiver Insertion Force: 40N MAX.
- Transceiver Extraction Force: 11.5N MAX.
- Durability: 100 Cycles
- Working Temperature: -55˚C TO +85˚C



Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8322S00XXXX0

Plating Type

Definition	Code
Au 15u"	AJ
Au 30u"	BF

Packing Type

Definition	Code
Tray	A0
Tape & Reel	B0

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

SFP 4Gbps / SFP+10Gbps Cage
Single Row 1x1,1×2,1x4 and 1x6 Series

828 Series

Technical Data

Material

- Cage assembly: Copper Alloy
- Light pipe: PC,Clear
- Elastomeric Gasket: Carbon/Nickel in silicone
- EMI springs: Copper Alloy.

Applications and Features

- Compliant with MSA standard.
- Press-fit contact is compliant with IEC60352.
- Fix strong crocodile's snap style to
- Keep the entrance integrity avoid distortion in shape.
- Patent protected multi-piece composite structure.



Mechanical

- Transceiver Insertion Force: 40N Max.
- Transceiver Extraction Force: 11.5N Max.
- Durability: 100 Cycles
- Working Temperature: -55℃ TO +85℃

Notes: Please replace "X" with appropriate coding listed in the tables below

1x1 Series: Z - 8 2 8 1 1 1 X 0 0 X 0 X X 0

Tail Type Option		Cage Plating Option		Light Pipe Option		Enhanced EMI Gaskets Type	
Definition	Code	Definition	Code	Definition	Code	Definition	Code
Solder	0	Non-plated	0	W/O Light Pipe	0	Standard	0
Press-fit	1	Nickel Plated	1	W/ Light pipe	1	with EMI Spring	1
		Tin Plated	2			with Elastomeric Gasket	2
						with EMI Spring For PCI Express	3
						with Elastomeric Gasket For PCI Express	4
						Metal EMI Springs with PCI Heat Sink	P

1x2 Series: Z - 8 2 8 1 2 X 0 0 0 X X X 0

Tail Type Option		Special P/N Option		Light Pipe Option		EMI Style Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code
Solder	0	PCB Layout for M Type	0	Without Light Pipe	0	Spring Tabs	0
Press-fit	1	No Grounding Pin	3	With Light pipe	1	Metal EMI Springs	1
		PCB Layout for T Type	6			Elastomeric Gasket	2
						Metal EMI Springs For PCI Express	3

1x4 Series: Z - 8 2 8 1 4 X 0 0 0 X X X X

Tail Type Option		Special P/N Option		Light Pipe Option		EMI Style Option		Logo Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
Solder	0	PCB Layout for M Type	0	W/O Light Pipe	0	Spring Tabs	0	With LOGO for T type	0
Press-fit	1	No Grounding Pin	3	W/ Light pipe	1	Metal EMI Springs	1	Without LOGO for M type	1
		PCB Layout for T Type	6						
		Elastomeric Gasket (SFP+ 1X4)	Z						

1x6 Series: Z - 8 2 8 1 6 X 0 0 0 X X X 0

Tail Type Option		Special P/N Option		Light Pipe Option		EMI Style Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code
Solder	0	PCB Layout for M Type	0	W/O Light Pipe	0	Spring Tabs	0
Press-fit	1	No Grounding Pin	3	W/ Light pipe	1	Metal EMI Springs	1
		PCB Layout for T Type	6			Elastomeric Gasket	2

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

High Speed I/O Connector

SFP 4Gbps / SFP+ 10Gbps Stackable Connector & Cage Stackable 2X1 Series 2X1,2X2,2X3,2X4,2X5,2X6 and 2X8 Series

824 Series

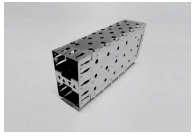
Technical Data

Material

- Cage: Copper Alloy
- Housing: High Temperature Thermoplastic Glass Filled, UL94 V-0, Black
- Kick-out Spring: Stainless Steel
- Contact: Copper Alloy with Au Plated
- Light Pipe: PC, Clear
- EMI Springs: Copper Alloy
- Elastomeric Gasket: Carbon/Nickel in silicone

Applications and Features

- Compliant with MSA standard.
- Press-fit contact is compliant with IEC 60352.
- Fix strong crocodile's snap style to Keep the entrance integrity Avoid distortion in shape.
- Patent protected multi-piece composite structure.

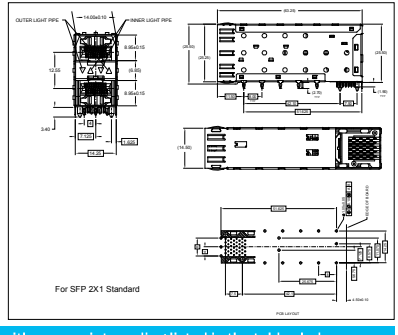


Electrical

- Contact Resistance: 70 mΩ Max.
- Insulation Resistance: 1000 MΩ Min.
- Withstanding Voltage: 300V AC

Mechanical

- Transceiver Insertion Force: 40N Max.
- Transceiver Extraction Force: 11.5N Max.
- Durability: 100 Cycles
- Working Temperature: -55 to 105℃



Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 2 4 X X 1 0 0 0 X X X 0

Position Option		Special P/N Option		Light Pipe Option		EMI Style Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code
2X1	21	Standard	0	W/O Light Pipe	0	Standard	0
2X2	22	No Grounding Pin	1	With & Outer Light Pipe	1	Metal EMI Springs	1
2X3	23			With Inner Light Pipe	2	Elastomeric Gasket	2
2X4	24			With Outer Light Pipe	3	Mixed	3
2X5	25						
2X6	26						
2X8	28						

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

High Speed I/O Connector

SFP/SFP+ DUST Cover

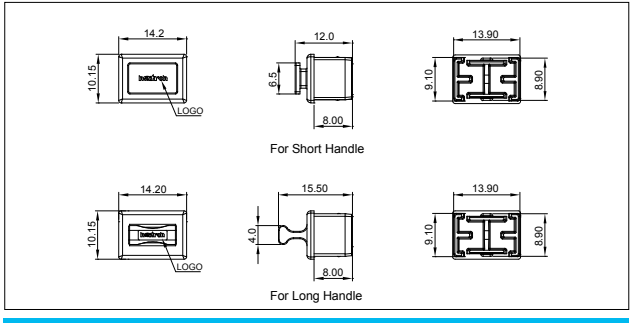
S891 Series

Technical Data

Material
- Thermoplastic
- RoHS Compliant

Applications and Features
- Dust cover suitable for SFP and SFP+ ports
- Long and short handles available
- Conductive and non-conductive options





Notes: Please replace "X" with appropriate coding listed in the tables below

Z - S 8 9 1 0 0 0 X 0 B X 2

Handle Type

Definition	Code
Long Handle	1
Short Handle	2

Material

Definition	Code
Conduction	1
No Conduction	2

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

XFP 10Gbps Connector

831 Series

Technical Data

Material

• Insulators	Polyester Thermoplastics Glass Fibre Filled,UL94V-0
• Contact	Copper Alloy With Au Plated

Applications and Features
- Capable of 10Gbps data signal speeds 15 or 30-microinch gold plating
- High-speed contact design
- SMT design in tape reel or tray packaging
- Advanced stamping technology for smooth contact surface

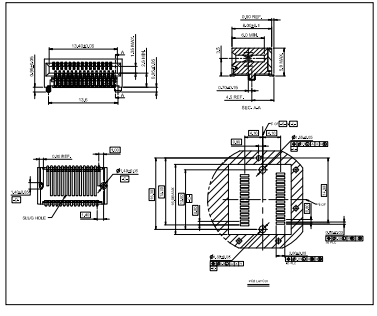


Electrical

• Contact Resistance:	△R 10 milliohms Max. for signal contacts
• Insulation Resistance:	1000 MΩ Min.
• Current Rating:	0.5 Amps Max. per contact

Mechanical

• Transceiver Insertion Force:	40 N Max.
• Transceiver Extraction Force:	30 N Max.
• Durability:	100 Cycles Min.
• Operating Temperature Range :	-20˚C To +85 ˚C



Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 3 1 0 0 1 1 X 0 1 1 X 1

Plating Type

Definition	Code
Au 15u"	0
Au 30u"	1

Packing Type

Definition	Code
Tape Reel	1
Tray	2

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

XFP 10Gbps Cage

838 Series

Technical Data

Material

- Body Cage: Copper Alloy
- Front EMI gasket: Stainless Steel
- Front flange: Zinc Alloy
- Heat sink: Aluminum
- Heat sink clip: Stainless Steel
- Upper rear EMI gasket: Conductive Form
- Lower rear EMI gasket: Conductive Elastomer

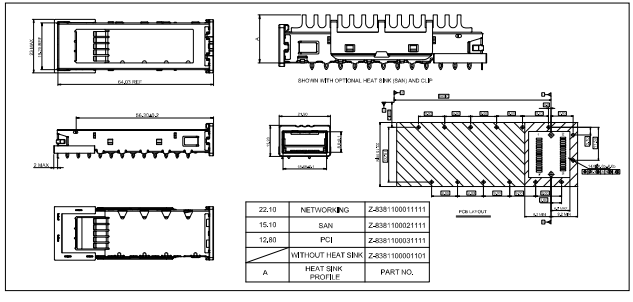
Applications and Features

- Compliant with MSA standard.
- Press-fit contact is compliant with IEC60352.
- Special design to keep the entrance integrity avoid distortion in shape.



Mechanical

- Transceiver Insertion Force: 40 N Max.
- Transceiver Extraction Force: 30 N Max.
- Durability: 100 Cycles Min.
- Operating Temperature Range : -20˚C To +85 ˚C



22.10	NETWORKING	Z-838110001111
15.10	SAN	Z-838110002111
12.80	PCI	Z-838110003111
	WITHOUT HEAT SINK	Z-838110000110
A	HEAT SINK PROFILE	PART NO.

Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 3 8 1 1 0 0 0 X 1 1 X 1

Heat sink Type

Definition	Code
Without Heat Sink	0
NET Heat Sink	1
SAN Heat Sink	2
PCI Heat Sink	3

Heat Sink Clip Type

Definition	Code
Without Clip	0
With Clip	1

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

High Speed I/O Connector

XFP/QSFP+ DUST Cover

S892 Series

Technical Data

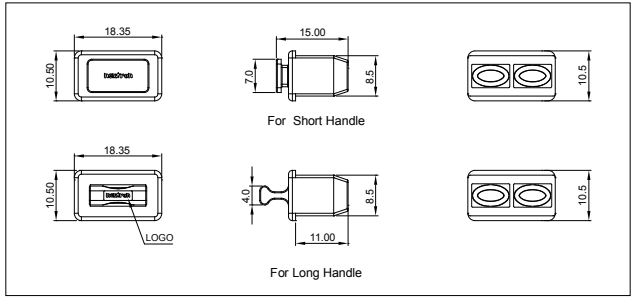
Material

- Thermoplastic
- RoHS Compliant

Applications and Features

- Dust cover suitable for XFP and QSFP+ ports
- Long and short handles available
- Conductive and non-conductive options





Notes: Please replace "X" with appropriate coding listed in the tables below

Z - S 8 9 2 0 0 0 X 0 B X 2

Handle Type

Definition	Code
Long Handle	1
Short Handle	2

Material

Definition	Code
Conduction	1
No Conduction	2

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

High Speed I/O Connector

QSFP+ 40Gbps Connector

835 Series

Technical Data

Material

- Insulators: Polyester Thermoplastics, Glass Fibre Filled,UL94V-0
- Contact: Copper Alloy with Au plated

Applications and Features

- Designs are based on the industry standard QSFP Multi-Source Agreement (MSA).
- The QSFP+ board mount connector is 38 position and 0.8mm pitch.
- High Speed Contact Design.
- High temp and IR reflow compatible versions are available.

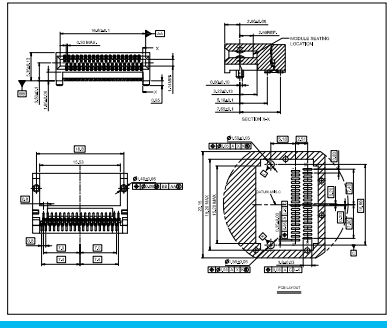


Electrical

- Contact Resistance: △R 10 Milliohms Max. for Signal contacts
- Insulation Resistance: 1000 MΩ Min.
- Current Rating: 0.5 Amps Max. per Contact

Mechanical

- Transceiver Insertion Force: 40 N Max.
- Transceiver Extraction Force: 30 N Max.
- Durability: 100 Cycles Min.
- Operating Temperature Range : -20℃ To +85 ℃



Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 3 5 0 0 1 1 X X 0 0 0 1

Plating Type

Definition	Code
Au 15u"	0
Au 30u"	1

Packing Type

Definition	Code
Tape Reel	1
Tray	2

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

QSFP+ 40Gbps/56Gbps Cage
1x1,1X2,1X3,1X4 and 1x6 Behind Bezel

834 Series

Technical Data

Material

- Body Cage: Copper Alloy
- EMI Spring: Stainless steel
- Front flange: Zinc alloy
- Heat sink: Aluminum
- Heat sink clip: Stainless steel
- Light pipe: Clear Polycarbonate

Applications and Features

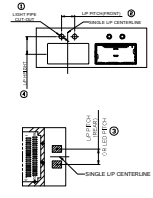
- Compliant with MSA standard.
- Lightpipe and heatsink options available.
- Press-fit and solder options available.
- Press-fit contact compliant with IEC60352.
- 360° EMI shielded



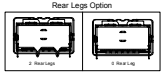
Mechanical

- Transceiver Insertion Force: 40 N Max.
- Transceiver Extraction Force: 30 N Max.
- Durability: 100 cycles Min.
- Operating Temperature Range: -20℃ To +85 ℃

Ordering information







Mating Bezel Table (mm)

CODE	L/P APPEARANCE	① L/P CUT-OUT	② L/P PITCH (FRONT)	③ L/P PITCH (REAR)	④ L/P HEIGHT	⑤ THE DIFFERENCE DIM. BETWEEN L/P AND FRONT FLANGE OR BEZEL THICKNESS	⑥ LED HEIGHT
0	WITHOUT L/P						
2	ROUND	Ø2.30	6.16	6.16	8.10	2.00	0.8~1.1
3	ROUND	Ø2.30	6.16	6.16	8.10	2.80	0.8~1.1
4	ROUND	Ø2.30	6.16	6.16	8.10	5.70	1.3~1.4
5	SQUARE	2.8*2.8	6.16	6.16	8.50	1.66	0.8~1.1

Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 3 4 B 0 X X P X X X X 1

Product Type

Definition	Code
1x1	11
1x2	12
1x3	13
1x4	14
1x6	16

Heat Sink Option

Definition	Code
Without Heat Sink	0
Networking Heat Sink (Heat Sink 13.5mm Tall)	1
SAN Heat Sink (Heat Sink 6.5mm Tall)	2
PCI Heat Sink (Heat Sink 4.2mm Tall)	3

Light Pipe Option

Definition	Code
Without Light Pipe	0
With Single Light pipe(Round)	1
With Dual Light pipe(Round)	2
With Single Light pipe(Square)	3
With Dual Light pipe(Square)	4

Mating Bezel Option

Definition	Code
See Table	0
	2
	3
	4
	5

Rear Legs Option

Definition	Code
0 Leg 1x1 Applicable	0
1 Leg All Applicable	1
2 Legs 1x1 Applicable	N

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

QSFP+ 40Gbps/56Gbps Cage
1x1,1x2,1x3,1x4 and 1x6 Thru bezel

834 Series

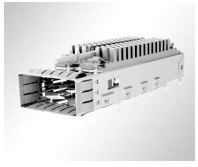
Technical Data

Material

- Body Cage: Copper Alloy
- EMI Spring: Stainless steel
- Heat sink: Aluminum
- Heat sink clip: Stainless steel
- Light pipe: Clear Polycarbonate

Applications and Features

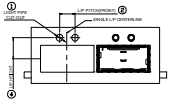
- Compliant with MSA standard.
- Lightpipe and heatsink options available.
- Press-fit and solder options available.
- Press-fit contact compliant with IEC60352.
- 360° EMI shielded

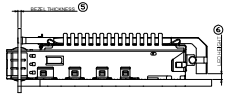


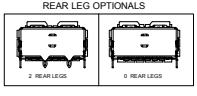
Mechanical

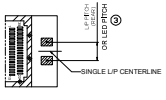
- Transceiver Insertion Force: 40 N Max.
- Transceiver Extraction Force: 30 N Max.
- Durability: 100 cycles Min.
- Operating Temperature Range: -20℃ To +85 ℃

Ordering information









Mating Bezel Table (mm)

CODE	L/P APPEARANCE	① L/P CUT-OUT	② L/P PITCH (FRONT)	③ L/P PITCH (REAR)	④ L/P HEIGHT	⑤ BEZEL THICKNESS	⑥ LED HEIGHT
0	WITHOUT L/P						
6	ROUND	Ø2.11	5.80	5.80	7.86	1.0~1.6	0.8~1.1
8	ROUND	Ø2.54	5.80	5.80	7.86	1.0~1.6	0.8~1.1

Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 3 4 T 0 X X P X X X X 1

Product Type		Heat Sink Option		Light Pipe Option		Mating Bezel Option		Rear Legs Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
1x1	11	Without Heat Sink	0	Without Light Pipe	0	See Table	0	2 Legs	0
1x2	12	Networking Heat Sink (Heat Sink 13.5mm Tall)	1	With Single Light pipe(Round)	1		6	0 Leg	N
1x3	13	SAN Heat Sink (Heat Sink 6.5mm Tall)	2	With Dual Light pipe(Round)	2		8		
1x4	14	PCI Heat Sink (Heat Sink 4.2mm Tall)	3						
1x6	16								

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

QSFP+ 40Gbps/56Gbps Cage
1x1,1x2,1x3,1x4 and 1x6 Elastomeric Gasket

834 Series

Technical Data

Material

- Body Cage: Copper Alloy
- EMI Spring: Stainless steel
- Gasket Frame: Stainless steel
- Heat sink: Aluminum
- Heat sink clip: Stainless steel
- Light pipe: Clear Polycarbonate
- Elastomer gasket: Carbon / Nickel in silicone

Applications and Features

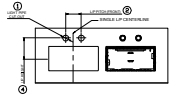
- Compliant with MSA standard.
- Lightpipe and heatsink options available.
- Press-fit and solder options available.
- Press-fit contact compliant with IEC60352.
- 360° EMI shielded

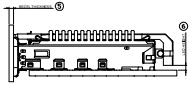


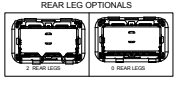
Mechanical

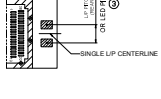
- Transceiver Insertion Force: 40 N Max.
- Transceiver Extraction Force: 30 N Max.
- Durability: 100 cycles Min.
- Operating Temperature Range: -20℃ To +85 ℃

Ordering information









Mating Bezel Table (mm)

CODE	L/P APPEARANCE	① L/P CUT-OUT	② L/P PITCH (FRONT)	③ L/P PITCH (REAR)	④ L/P HEIGHT	⑤ BEZEL THICKNESS	⑥ LED HEIGHT	REMARK
0	WITHOUT L/P							1x1,1x2,1x3,1x4,1x6 APPLICABLE
6	ROUND	Ø2.11	5.80	5.80	7.86	1.0~1.6	0.8~1.1	1x1 APPLICABLE
7	ROUND	Ø2.67	5.80	5.80	7.75	1.0~1.6	0.8~1.1	1x2,1x3,1x4,1x6 APPLICABLE

Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 3 4 E 0 X X P X X X X 1

Product Type		Heat Sink Option		Light Pipe Option		Mating Bezel Option		Rear Legs Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
1x1	11	Without Heat Sink	0	Without Light Pipe	0	See Table	0	2 Legs	0
1x2	12	Networking Heat Sink (Heat Sink 13.5mm Tall)	1	With Single Light pipe(Round)	1		6	0 Leg	N
1x3	13	SAN Heat Sink (Heat Sink 6.5mm Tall)	2	With Dual Light pipe(Round)	2		7		
1x4	14	PCI Heat Sink (Heat Sink 4.2mm Tall)	3						
1x6	16								

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

QSFP+ 40Gbps/56Gbps Cage
2x1,2x2 and 2x3 Type

844 Series

Technical Data

Material

- Body Cage: Stainless Steel
- EMI Spring: Stainless Steel
- Gasket Frame: Stainless Steel
- Light Pipe: Clear Polycarbonate
- Elastomer Gasket: Carbon / Nickel in silicone
- Housing: High Temperature Thermoplastic Glass Filled,UL94 V-0, Black
- Contact: Copper Alloy with Au Plated

Applications and Features

- Compliant with MSA standard.
- Lightpipe and heatsink options available.
- Press-fit and solder options available.
- Press-fit contact compliant with IEC60352.
- 360° EMI shielded

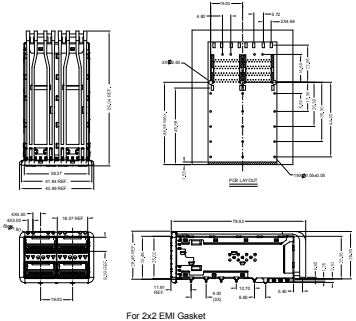


Electrical

- Voltage: 30V AC (RMS)/DC Max
- Current: 0.5A Max
- Contact Resistance: ≤ R 10 Milliohms Max. for Signal Contacts
- Insulation Resistance: 1000 MΩ Min.
- Withstanding Voltage: 300V DC

Mechanical

- Connector Mate Forces (Module only): 2.5 N/contact pair Max. insertion force
- Connector Un-mate Forces (Module only): 0.5 N/contact pair Max. withdrawal force
- Durability: 100 cycles Min.
- Operating Temperature Range: -40℃ To +85 ℃



For 2x2 EMI Gasket

Notes: Please replace "X" with appropriate coding listed in the tables below

Z - 8 4 4 X 0 X X P 0 X X X 0

Product Feature		Product Type		Light Pipe Option		Vent Holes Option		Rear Legs Option	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
Behind Bezel	B	2x1	21	Without Light Pipe	0	With Circular Vent Holes	0	0 Leg	0
Thru Bezel	T	2x2	22	With Inner & Outer Light Pipe (Triangular)	1	With Rectangular Vent Holes	1	2 Legs / Port	1
EMI Gasket	E	2x3	23	With Inner Light Pipe (Triangular)	2				
				With Outer Light Pipe (Triangular)	3				
				With Inner & Outer Light Pipe (Triangular) & With Upper Light Pipe (Triangular)	4				

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed I/O Connector

Mini SAS HD Internal Connector
1x1,1x2 and 1x4 Right Angle Receptacle

H02 Series

Technical Data

Material

- Insulators: High Temperature Thermoplastics, UL94V-0
- Contact: Copper Alloy
- Plating: Gold Over Nickel for Contact Area, Tin Over Nickel for Tail

Applications and Features

- The connector consists of housing with double 18-position receptacle ports and with compliant pin contacts on 0.75mm centerline spacing.
- Each port has a card entry slot that accepts an integrated circuit card housed in the mating plug. The connector has a single port with two card slot openings and is configured as 1X1,1X2 and 1X4 assemblies. The connector compliant pin contacts are press-fit mounted into a PC board with plated finished through holes.

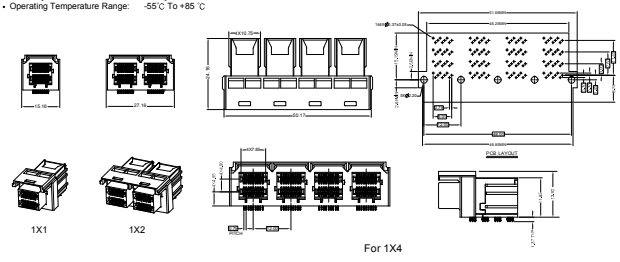


Electrical

- Current Rating: 0.5A Max. Per Pin
- Voltage Rating: 30V DC Max. Per Pin
- Contact Resistance: 50mΩ MAX. Per Pin

Mechanical

- Transceiver Insertion Force: 60 N Max.
- Transceiver Extraction Force: 30 N Max.
- Durability: 250 Cycles Min.
- Operating Temperature Range: -55℃ To +85 ℃



1X1 1X2

For 1X4

Notes: Please replace "X" with appropriate coding listed in the tables below

R - H 0 2 R 0 1 1 1 X X 0 X 0

Contact Option	
Definition	Code
1x1	04
1x2	08
1x4	16

Type Option	
Definition	Code
Right Angle	R
Vertical	V

※Vertical Type Under Development.

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed Optical Electrical Cable

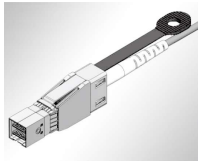
Mini-SAS HD Active Optical Cable

AOC Series

Technical Data

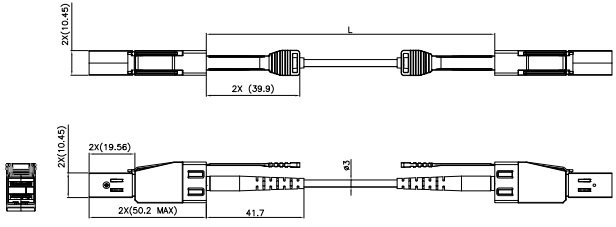
Applications

- Storage, Switch, & Server Systems
- Workstations
- High-Performance Computing (HPC)



Features

- Compliant to SAS-3 of 12-Gbps lane speed
- Backwards compatible to 6-Gbps SAS-2.1 of optical module capable systems
- 4Tx/Rx, Full-Duplex AOCs, Maximum aggregate speed of 48-Gbps
- Bit-Error-Rate (BER) better than 10-12
- Link length up to 100-m via OM3 MMF
- Round cable with small 3.0-mm outer diameter for flexible routing and easy cable management
- Connector compliant to SFF-8644
- Management interface compliant to SFF-8636
- Out-of-Band (OOB) Signal Support



Notes: Please replace "X" with appropriate coding listed in the tables below

R - SA4C04012MSMLXXX

Channel Number		Application Speed		Application Type		Fiber Type		Fiber Length	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
4 channel	04	12G	012	MiniSAS HD	MS	Bondle+OM2+Orange	B	1M	001
						Bondle+OM3+Aqua(>30M)	M	⋮	⋮
								150M	150

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed Optical Electrical Cable

40 & 56Gbps QSFP+ Active Optical Cable

AOC Series

Technical Data

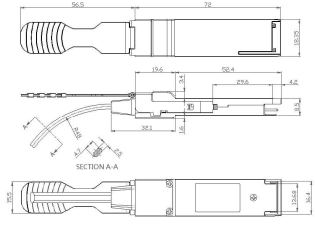
Applications

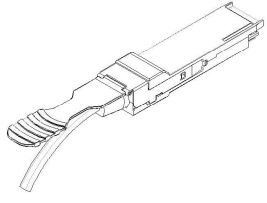
- InfiniBand FDR, QDR, DDR, and SDR
- 40GBASE SR4 Ethernet links
- 4G/8G/10G Fiber Channel
- SATA/SAS Storage
- HPC Interconnects
- Proprietary Interconnections



Features

- 4-channel bi-directional AOC with aggregate bandwidth of 40 & 56-Gbps (Electrical Interface Only)
- Compliant to SFF-8436 QSFP+ Specification Revision 4.1
- Supports 40&56 Gbps aggregate data-rate links up to 100-m
- Low power consumption of max 1.5 W (Compliant to Power Level 1)
- Full Digital Diagnostics Monitor Interface
- Hot pluggable electrical interface
- 0 to 70°C case temperature operating range
- RoHS Compliance and Lead-Free





Notes: Please replace "X" with appropriate coding listed in the tables below

R - SA4C04XXXQAXLXXX

Channel Number		Application Speed		Application Type		Fiber Type		Fiber Length	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
4 channel	04	10G	010	QSFP AOC	QA	Ribbon+OM2+Orange	R	1M	001
		14G	014			Ribbon+OM3+Aqua(>30M~100m)	S	⋮	⋮
		25G	025			Ribbon+OM4+Aqua(>100m)	U	150M	150

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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High Speed Optical Electrical Cable

Transceiver Series 40Gbps QSFP+ Optical Transceiver Module

Technical Data

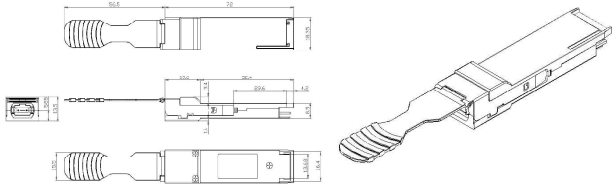


Applications

- 40GBASE-SR4 Ethernet links
- InfiniBand QDR, DDR, and SDR
- 4G/8G/10G Fiber Channel
- SATA/SAS Storage
- HPC Interconnects
- Proprietary Interconnections

Features

- Compliant with 40GBASE-SR4 per IEEE 802.3ba D3.2 and SFF-8436 QSFP+ MSA Rev. 4.1
- Operating at 10.3125-Gbps per lane with 64b/66b coded data
- Low power dissipation < 1.5W (Power Level-1)
- Full Digital Diagnostics Monitor Interface
- Hot pluggable electrical interface
- Standard 12/8 lane optical fiber with MPO pluggable optical connector.
- 0 to 70°C case temperature operating range
- 100/150-m Link Length via OM3/OM4 with MPO Optical Connector
- RoHS Compliance and Lead-Free
- SR4, iSR4, eSR4 Models available



Notes: Please replace "X" with appropriate coding listed in the tables below

R - SA4C040101XXXM000

Channel Number		Application Speed		Application Type		Fiber Type	
Definition	Code	Definition	Code	Definition	Code	Definition	Code
4 channel	04	10G	010	QSFP SR4	QT	no fiber (Transceiver)	X
				QSFP e-SR4	QE		
				QSFP i-SR4	QI		

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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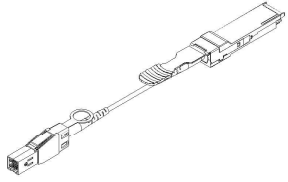
High Speed Optical Electrical Cable

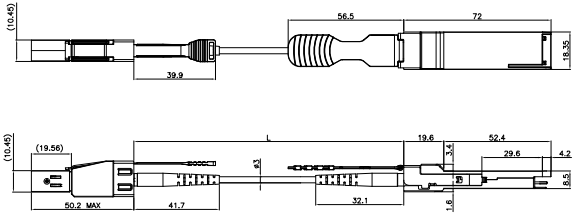
AOC Series QSFP+ to MiniSAS HD Active Optical Cable

Technical Data

Features

- Backwards compatible to 6-Gbps SAS-2.1 of optical-mode capable systems with out-of-band (OOB) signal supported
- 4Tx/Rx, Full-Duplex AOCs, Maximum aggregate speed of 48-Gbps for SAS3.0
- Bit-Error-Rate (BER) better than 10-12
- Link length up to 100-m via OM3 MMF
- Round cable with small 3.0-mm outer diameter for flexible routing and easy cable management
- MiniSAS HD and QSFP+ connector compliant to SFF-8644 and SFF-8436, respectively
- Management interface compliant to SFF-8636





Notes: Please replace "X" with appropriate coding listed in the tables below

R - SA4C040112QMXLXXX

Channel Number		Application Speed		Application Type		Fiber Type		Fiber Length	
Definition	Code	Definition	Code	Definition	Code	Definition	Code	Definition	Code
4 channel	04	12G	012	QSFP to MiniSAS HD	QM	Bondle+OM2+Orange	B	1M	001
						Bondle+OM3+Aqua(>30M)	M	⋮	⋮
								150M	150

Note:Dimensions are shown in Millimeters . Dimensions are for reference only

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